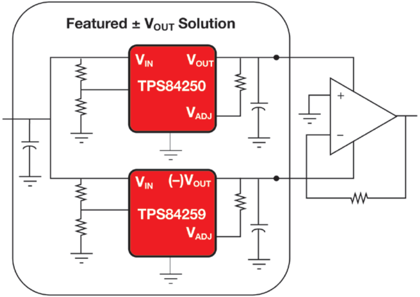
TPS84K Integrated Power Modules

Small, Easy to Use and Optimized for Performance

- Integrated inductor and passives require as few as 3 external components
- Small low-profile QFN packaging capable of 260°C reflow
- Low-package thermal resistance delivers full current at Ta = 85°C
- Low noise: All modules meet EN55022 Class B emissions
- Wide operating temperature: Up to 125°C Tj



NEW

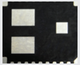
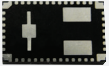
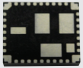
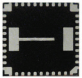
TPS84250

- 7V to 50V input – survives 65V transients
- 2.5V to 15V output up to 2.5A
- Small 9x11x2.8mm QFN package

NEW

TPS84259

- 4.5V to 40V input
- –3V to –17V output up to 15W
- Small 9x11x2.8mm QFN package

Device	V_{IN} (V)	I_{OUT} (A)	V_{OUT} (V)	θ_{JA} (°C/W)	F_{SW} (kHz)	QFN Package
TPS84210 TPS84410 TPS84610	2.95 to 6	2 4 6	0.8 to 3.6	12 12 12	500 to 2000	9 x 11 x 2.8 mm 
TPS84320 TPS84620 TPS84621	4.5 to 14.5	3 6 6	0.8 to 5.5 1.2 to 5.5 0.6 to 5.5	13 13 13	330 to 780 480 to 780 250 to 780	9 x 15 x 2.8 mm 
TPS84250 TPS84259	7 to 50 4.5 to 40	2.5 2	2.5 to 15 –3 to –17	14 14	400 to 1000 500 or 800	9 x 11 x 2.8 mm 
TPS84A20	4.5 to 17	10	0.6 to 5.5	TBD	200 to 2000 180° out of phase	10 x 10 x 4.3 mm 

All devices have: INH, PG, Adj. UVLO, Adj. Soft Start, Track, and Sync (CLK) pin except for TPS84259 (no PG and Track). *Preview products are listed in* ***bold blue.***

For evaluation boards, samples, datasheets, WEBENCH®/SwitcherPro™ models visit

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